



App. No. 09/830,490
Response Under 37 CFR § 1.116
Expedited Procedure
Examining Group 1734
Amdt. dated April 17, 2003
Reply to Office Action of December 26, 2002

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Amendments to the Specification:

Please replace the paragraph beginning at page 12, line 13, with the following rewritten paragraph:

C In this embodiment, as shown in Fig. 4, ~~on~~one of the pair of sheet members 20, 22 (sheet member 20 in Fig. 4) can be composed of a release sheet. In this instance, after the card is formed, an adhesive layer can be exposed by stripping the release sheet from the produced IC cards, so that the IC cards can be stuck to, for example, a surface of a corrugated cardboard box through the exposed adhesive layer as IC labels. Thus, the IC cards can be utilized in the information management for a physical distribution system and the like.